
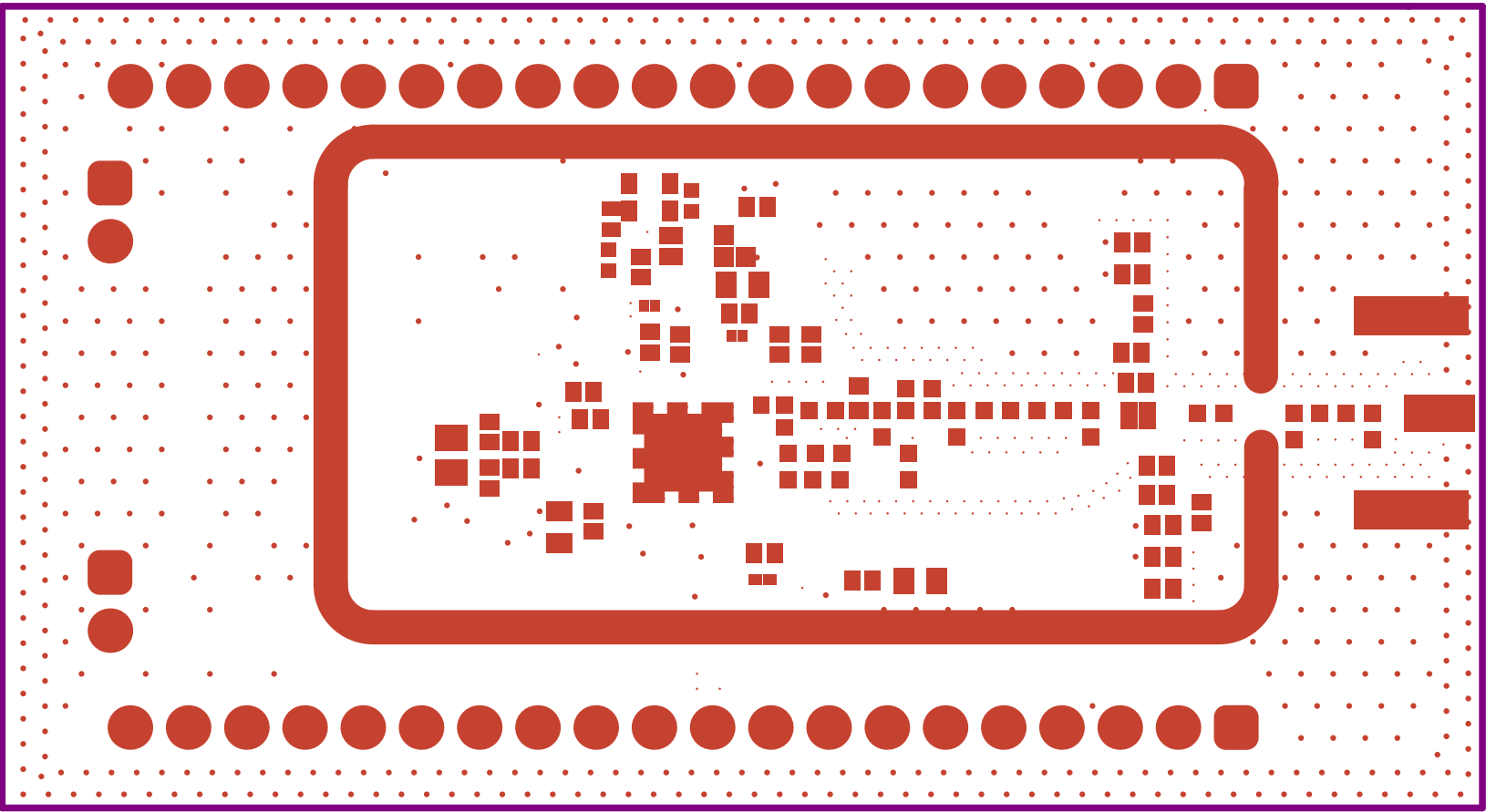

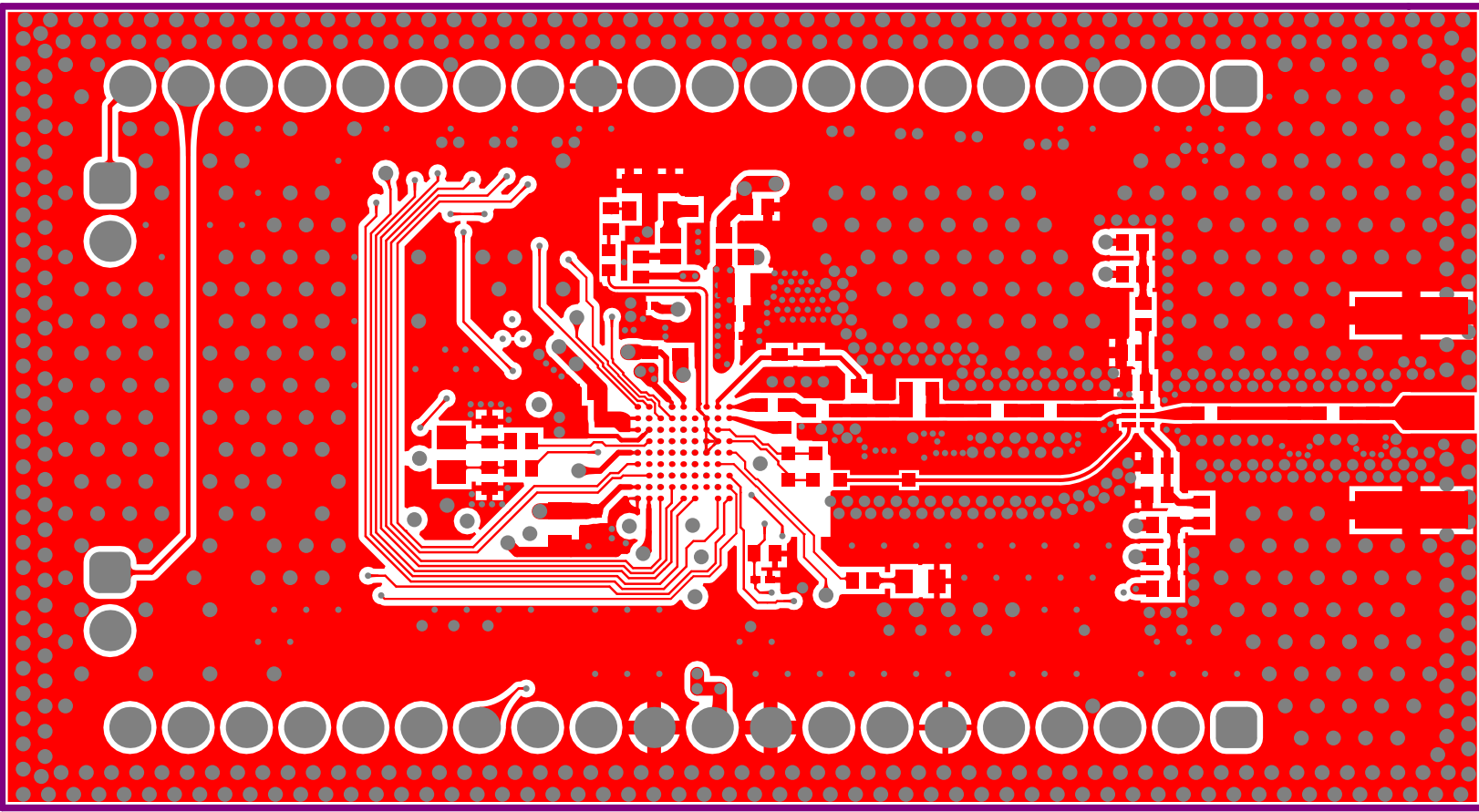



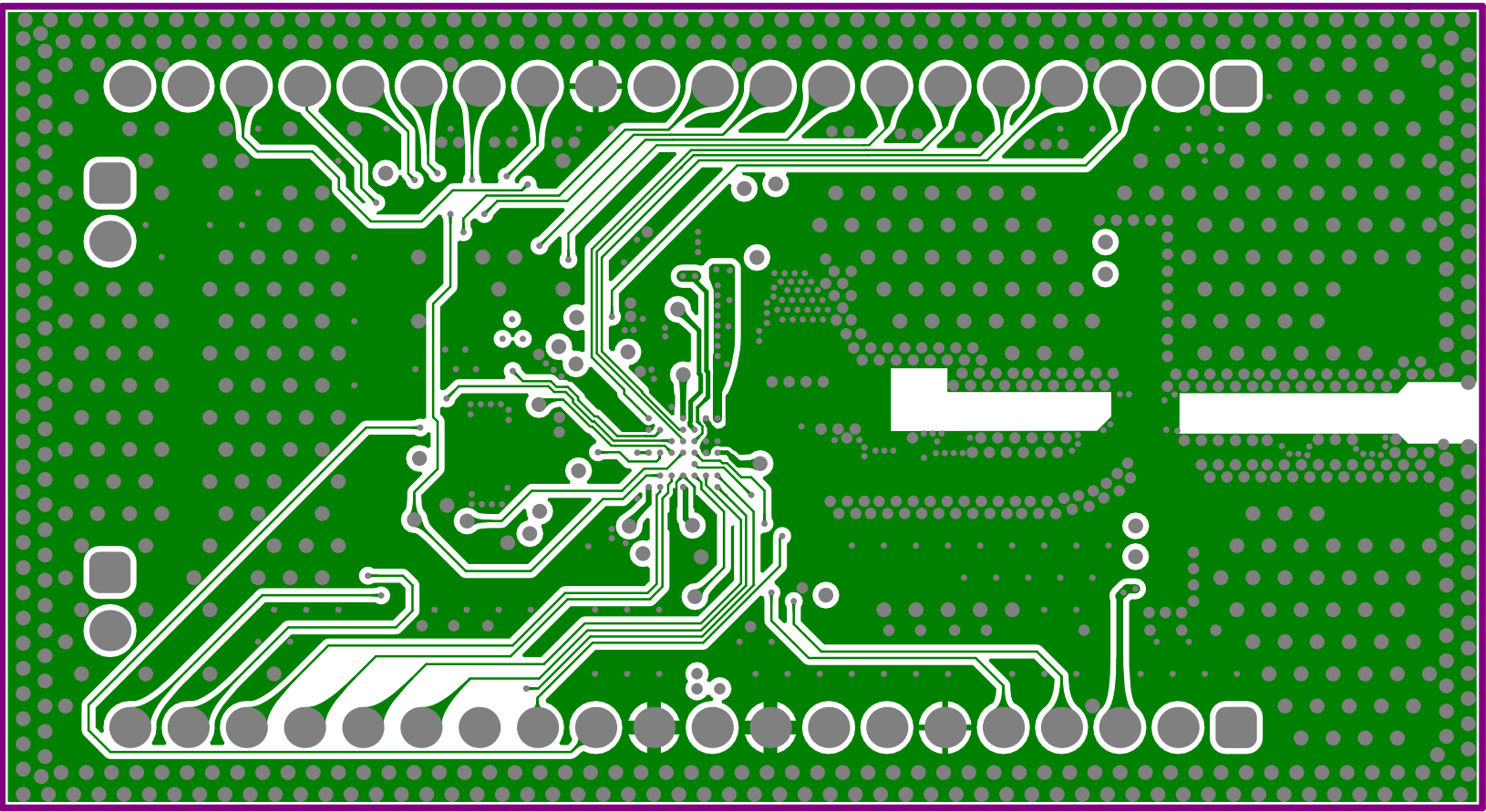
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	




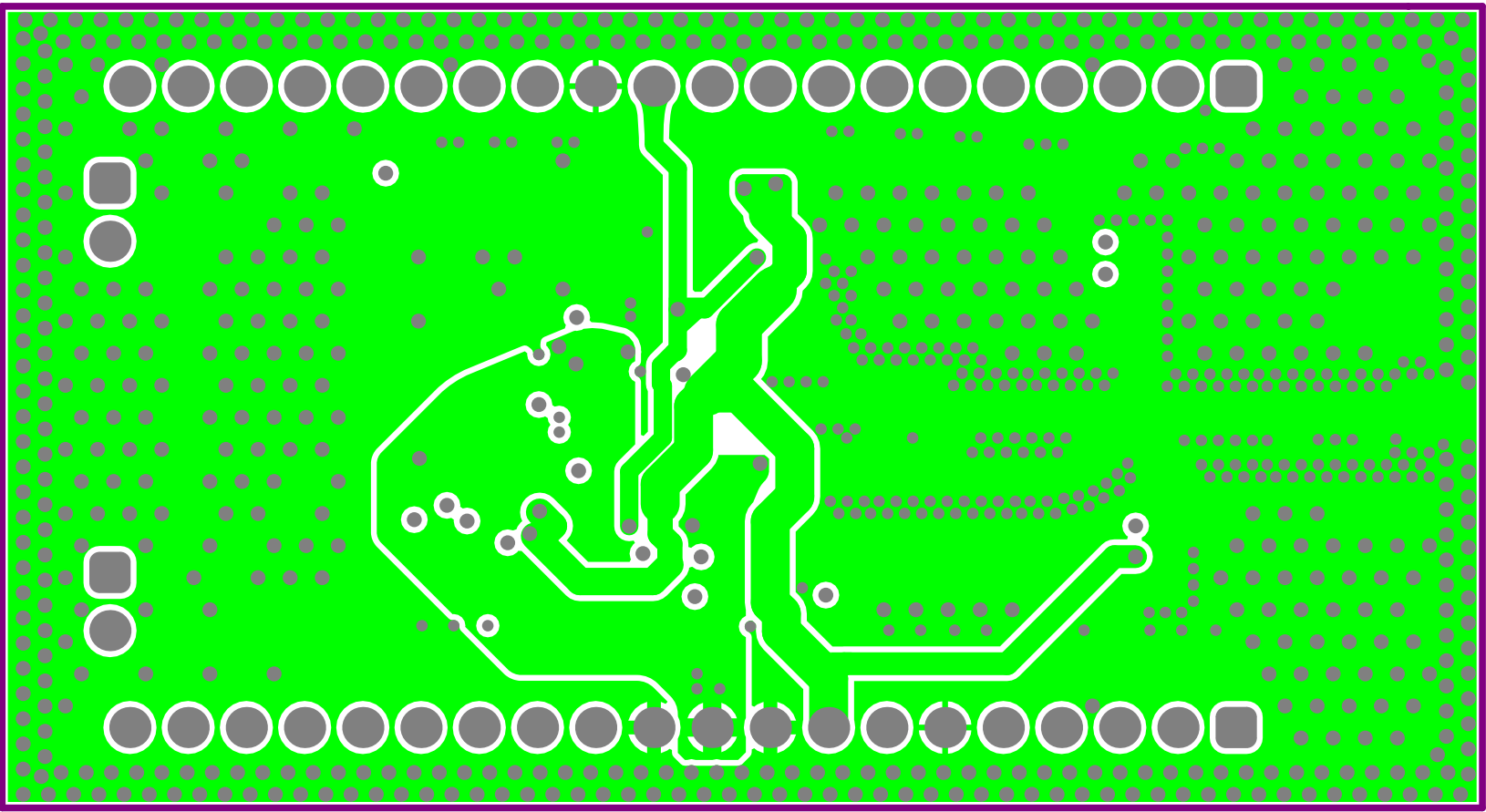
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	




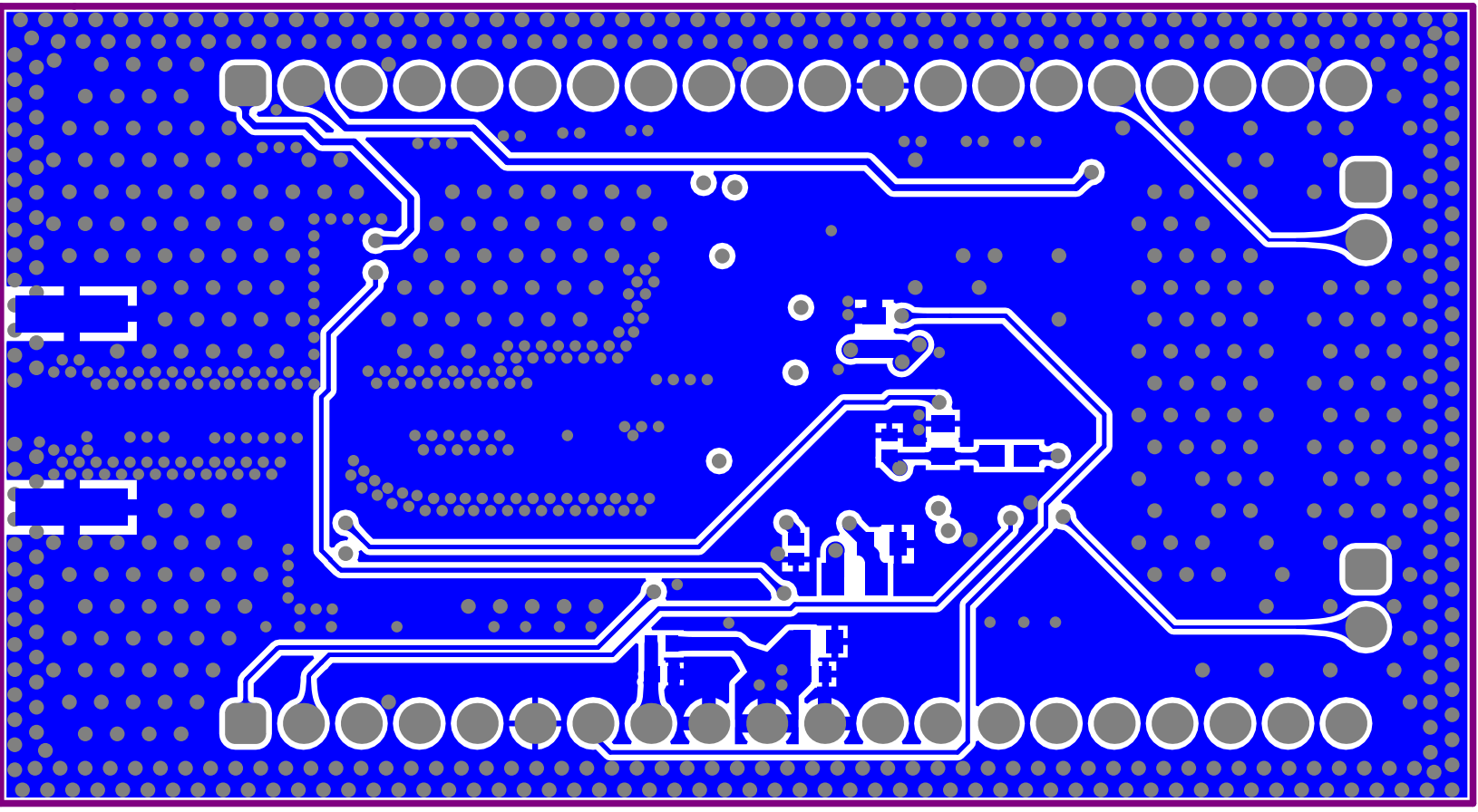
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	




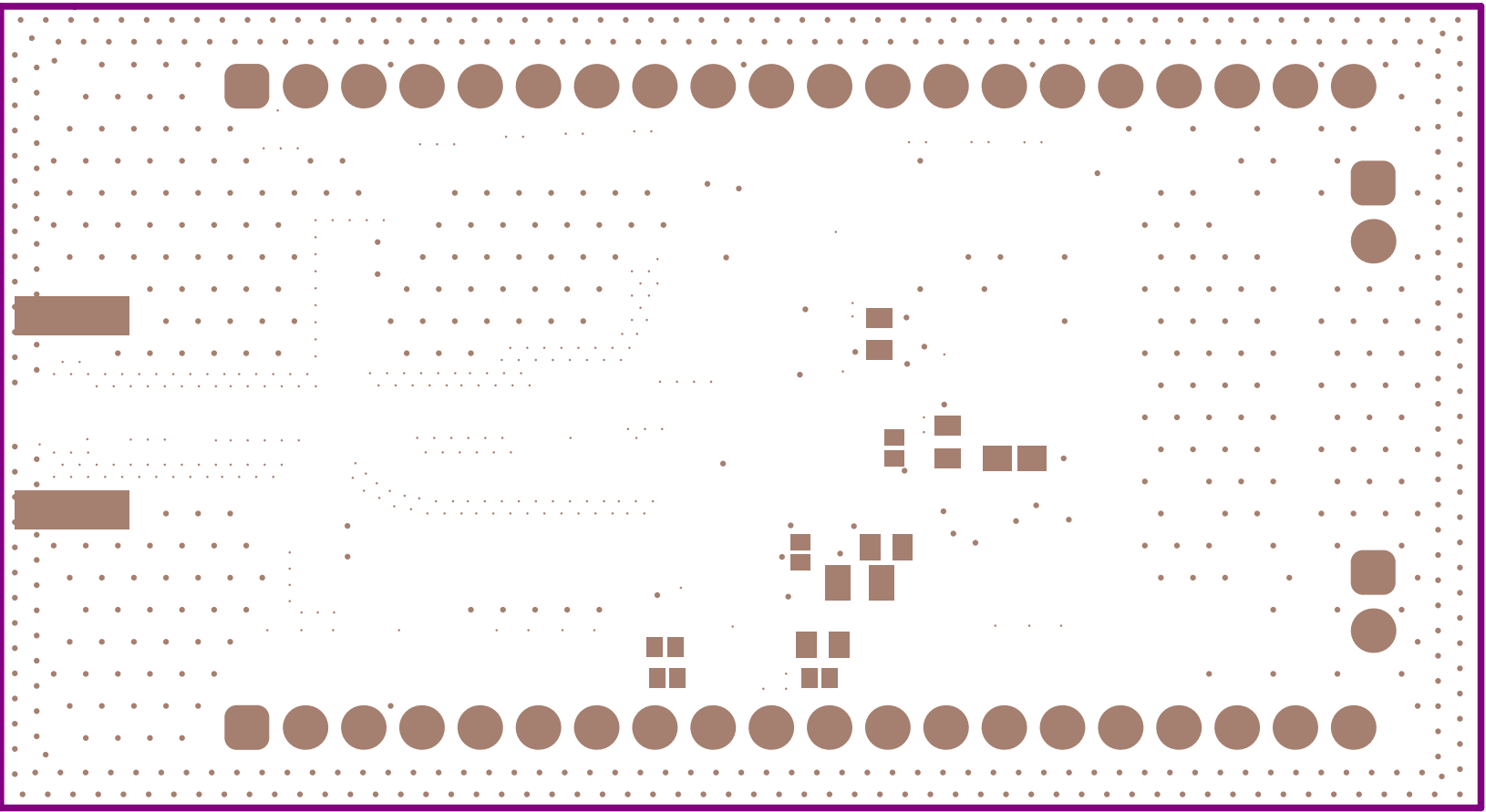
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: MidLayer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	




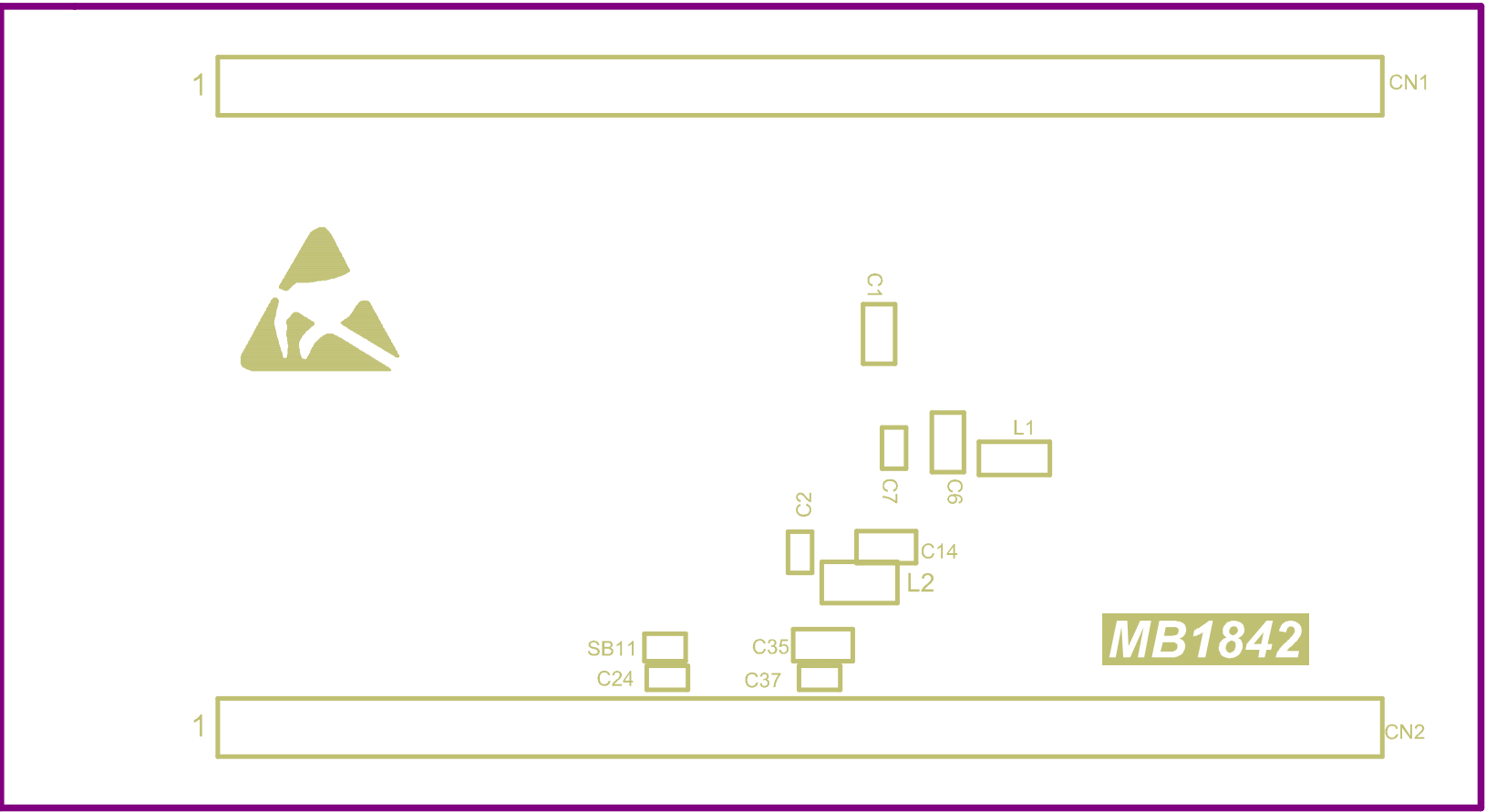
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: MidLayer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	




Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	



Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	



Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	2.01mil	3.7	
1	Top Layer		1.38mil		
	Dielectric 1	1 x 2116	4.25mil	3.8	
2	MidLayer 1		1.38mil		
	Dielectric 2	FR4	27.95mil	5	
3	MidLayer 2		1.38mil		
	Dielectric 3	1 x 2116	4.25mil	3.8	
4	Bottom Layer		1.38mil		
	Bottom Solder	Solder Resist	2.01mil	3.7	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
□	44	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>				-	-
✱	890	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>				-	-
	934 Total												

IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	22.9	5.9	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☒ GREEN

☐ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

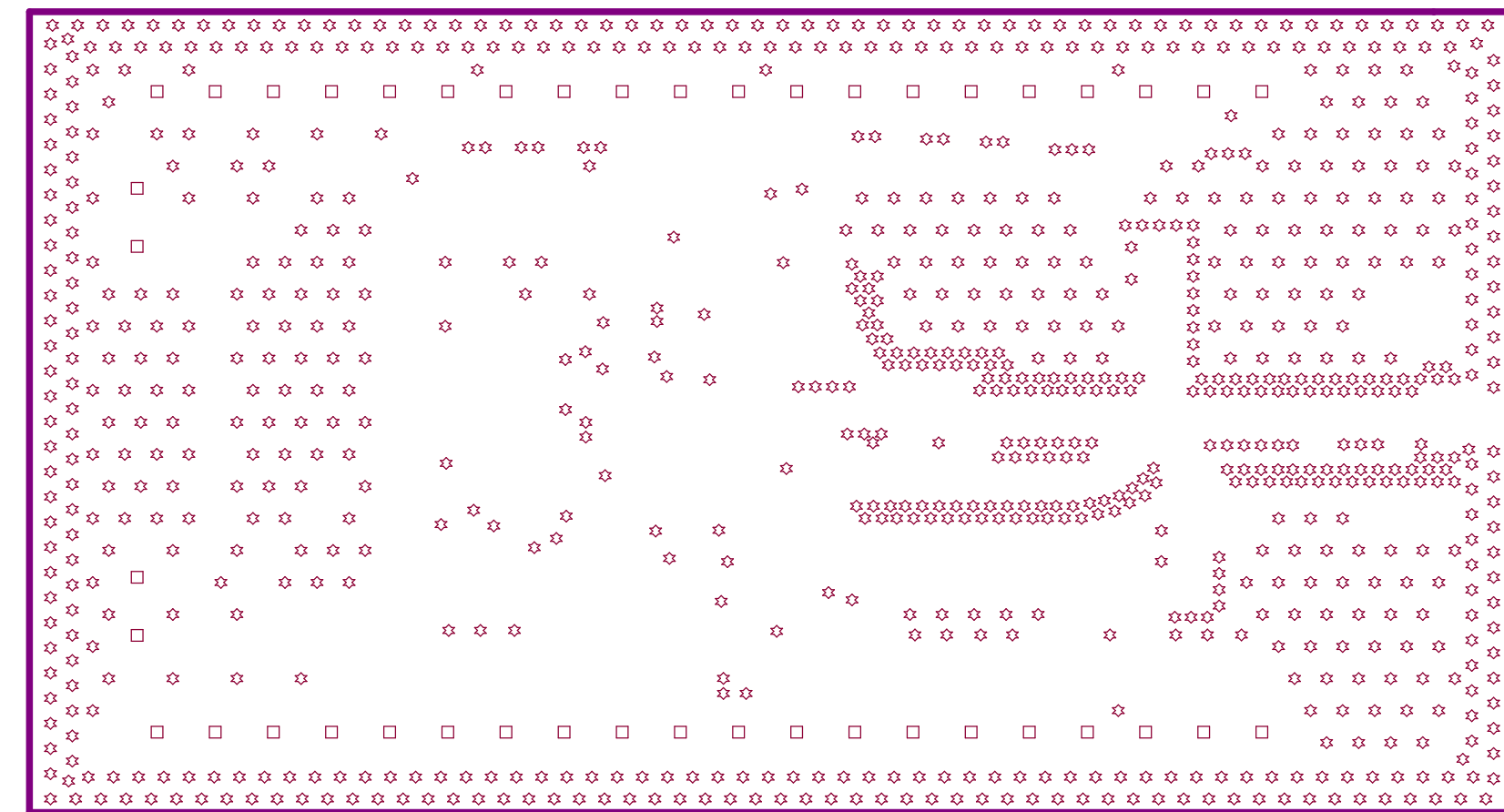
PLUG MATERIAL :


☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB1842	
Date: 23-03-2022	Rev: A	